

**SSN16LF BOM-style material declaration. BI Technologies Corporation**

1/24/2011

No content banned per EU RoHS. Average mass of SSN16LF thin film network is 0.15 grams each. Prepared by Eric Arnold (714) 447-2565  
Weights above 1 milligram rounded to the nearest mg. Values less than 1 milligram given in scientific notation.

Sub-component	Material	% of total mass	Substance name	CAS #	Substance Weight (grams)	Special classification
Die	substrate	3.41%	Si	7440-21-3	0.005	
		insignificant	SiO <sub>2</sub> , amorphous	7631-86-9	trace	
	nichrome resistor	0.0003%	NiCrOx	mix of 7440-02-0, 7440-47-3, & 1308-38-9	4.30E-07	
		insignificant	TiW (10/90)	mix of 7440-32-6 & 7440-33-7	trace	
	gold conductor	0.01%	Au	7440-57-5	1.45E-05	
	BCB passivation	0.01%	dvs-BCB, divinylsiloxane-bis-benzocyclobutene	124221-30-3	1.38E-05	
Leadframe	copper alloy	38.1%	Cu	7440-50-8	0.056	
			Fe	7439-89-6	0.001	
			P	7723-14-0	1.71E-05	
			Zn	7440-66-6	6.84E-05	
	matte Sn plating	0.84%	Sn	7440-31-5	0.001	
		0.98%	Ag	7440-22-4	0.001	
Die adhesive	conductive epoxy	0.91%	Ag	7440-22-4	0.001	
			trade secret	unknown	2.73E-04	non-hazardous
Wire bonds	gold	0.09%	Au	7440-57-5	1.34E-04	
Molding compound	filled epoxy	55.60%	carbon black	1333-86-4	4.16E-04	
			epoxy resin, cresol	29690-82-2	0.002	
			novolac			
			SiO <sub>2</sub> , fused silica	60676-86-0	0.073	
			trade secret	unknown	0.008	non-hazardous
Ink marking	epoxy	0.04%	trade secret	unknown	6.60E-05	non-hazardous